

International Application No.: PCT/JP2005/019286

U.S. Patent Application No.: Unknown

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Page 2 of 8

AMENDMENTS TO THE SPECIFICATION:

A substitute specification and a marked-up copy of the English translation of the originally filed PCT application are attached hereto.

Please replace the Title of the Invention originally filed with the above-identified patent application with the following new Title:

MULTILAYER SUBSTRATE WITH BUILT-IN CHIP-TYPE ELECTRONIC
COMPONENT AND METHOD FOR MANUFACTURING THE SAME